

SJ-601TR

Crosslinkable Semiconductive Shielding Compound

Overview

SJ-601TR is a outstanding crosslinkable semiconductive polyethylene copolymer compound for conductor and bonded insulation shielding of medium voltage XLPE insulated power cable.

SJ-601TR is compatible with copper and aluminum conductors. SJ-601TR provides a super-smooth surface yielding virtually perfect interface between the extruded shield and insulation. Significantly improved cable performance can be expected.

SJ-601TR has stable anti-tracking characteristics.

Specifications

This compound has no specifications.

The user should select and use the application suitable for the characteristics.

Properties

This TDS is typical data only and are not to be construed as specifications. Users should results their own test. Tests are conducted on compression molded slabs cured 15 minutes at 180℃.

Physical	Value (English)	Value (SI)	Test Method
Density	1.05 g/cm³	1.05 g/cm³	ASTM D 1505
Moisture Content	300 ppm	300 ppm	ASTM D 6869
Melt Flow Rate[125°C(257°F)/10.0 kg]	4.00 g/10min	4.00 g/10min	ASTM D 1238
Brittleness temperature	<-70 °C	<-70 °C	ASTM D 746
Mechanical	Value (English)	Value (SI)	Test Method
Ultimate Tensile Strength	2973 psi	20.5 Mpa	ASTM D 638
Elongation at Break	350 %	350 %	ASTM D 638
Retention of Tensile Strength After Ageing - 135°C[275°F], 168hrs	90 %	90 %	IEC 60811-401
Retention of Elongation After Ageing - 135°C[275°F], 168hrs	90 %	90 %	IEC 60811-401
Electrical	Value (English)	Value (SI)	Test Method
Time to track at 4.5kV	>120 h	>120 h	IEC 60587
Volume Resistivity at 23 ℃[73.4°F]	1.0x10 ¹⁶ Ωcm	1.0x10 ¹⁶ Ω cm	ASTM D 257

Processing

SJ-601TR provides excellent surface finish and outstanding output rates over a broad range of extrusion conditions.

SJ-601TR requires melt stock temperatures in the range of 110°C to 120°C for best results. Lower melt temperatures may result in unmelted extrudate and higher melt temperatures may result in extrudate scorch and It can even trigger die-drools.

The curing configuration : the maximum cable surface temperature in the curing zone should be maintained below 400°C. If the surface temperature of the cable in the curing zone is over

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400°C, it may cause cracks in the cable, so careful temperature control is required. Dehumidified hopper drying at 60~70°C for up to 4 hours prior to extrusion could help remove moisture. Specific processing conditions depend on equipment and cable dimensions. Optimum conditions by conventional practices should be established.

Packing & Storage

Packed in 600kg polybag lined carton box.

Recommended maximum storage period is 12months unopened and in original packaging after the manufacture.

Stored at room temperatures

86 °F

30 ℃

The shelf life of this product is 1 year from the date of manufacture.

Safety

Please contact Seji Chemical for Material Safety Data Sheet.

Disclaimer

Information contained in this data sheet is up-to-date and correct as at the date of issue.

Seji chemical Co., Ltd. cannot control or anticipate the conditions under which this product may be used, each user should review the information in specific context of the planned use.

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